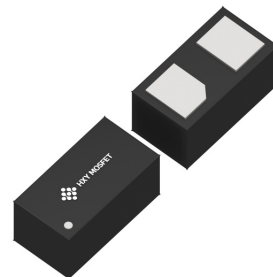




Discription

The HESDNC5VB1GF-A protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN0603-2L

Features

- ★ Small Body Outline Dimensions:
0.61mm x 0.31 mm
- ★ Low Body Height: 0.28 mm
- ★ Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 (> 16 kV) per Human Bod Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ These are Pb-Free Devices
- ★ We declare that the material of product compliance with RoHS requirements.



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HESDNC5VB1GF-A	DFN0603-2L	15000

Absolute Ratings ($T_{amb}=25^{\circ}\text{C}$)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	80	W
T_L	Maximum lead temperature for soldering during 10s	260	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
T_{op}	Operating Temperature Range	-40 to +125	$^{\circ}\text{C}$
T_j	Maximum junction temperature	150	$^{\circ}\text{C}$
	IEC61000-4-2 (ESD)	air discharge contact discharge	± 30 ± 30 KV



Electrical Characteristics

	V_{RWM} (V)	$I_{R1}(\mu A)$ @ V_{RWM}	$I_{R2}(\mu A)$ @ $V_R=3.5V$	V_{BR} (V) @ I_T (Note 2)	I_T	V_C (V) @ $I_{PP} = 1 A$ (Note 3)	V_C (V) @ MAX I_{PP} (Note 3)	$I_{PP}(A)$ (Note 3)	$P_{PK}(W)$ (Note 3)	C (pF)
Device	Max	Max	Max	Min	mA	Max	Max	Max	Max	Typ
HESDNC5VB1GF-A	5.0	0.5	0.3	5.6	1.0	9	10	8	80	15

Other voltage available upon request.

2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C

3. Surge current waveform per Figure 1.

Typical Characteristics

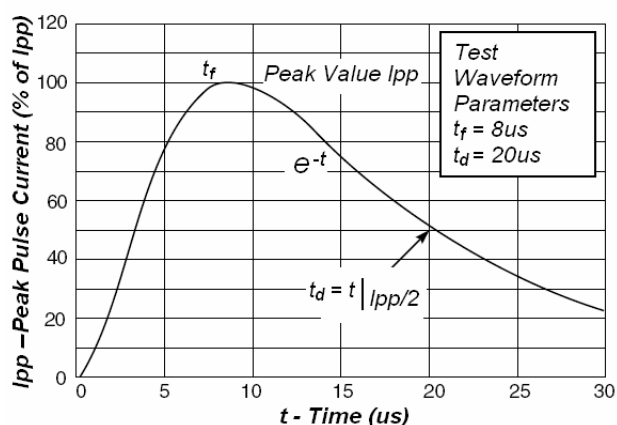


Fig1. Pulse Waveform

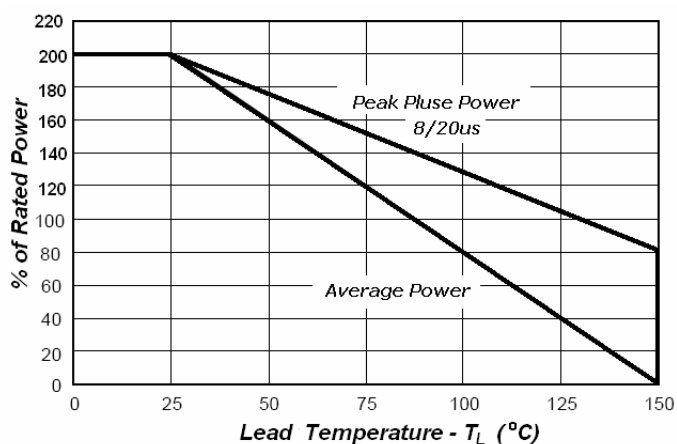
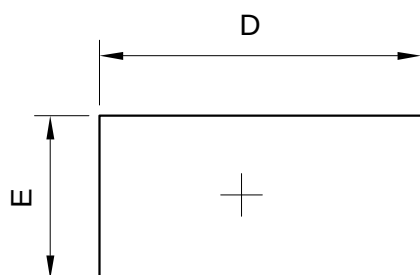


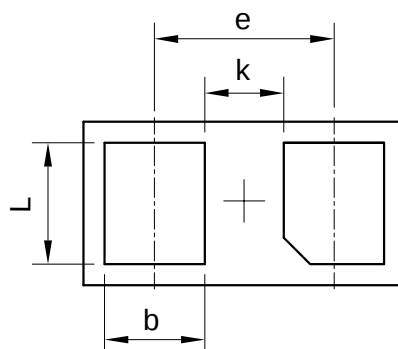
Fig2.Power Derating Curve



Package Outline Dimension



TOP VIEW



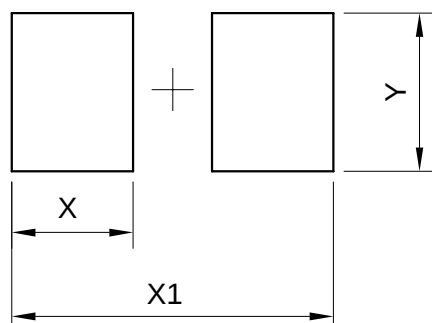
BOTTOM VIEW

DFN0603-DL			
Dim	Min	Typ.	Max
D	0.58	0.61	0.64
E	0.28	0.31	0.34
e	-	0.34	-
L	0.20	0.23	0.26
b	0.16	0.19	0.22
A	0.25	0.28	0.31
k	0.12	0.15	0.18
All Dimensions in mm			



SSIDE VIEW

Suggested Pad layout



DFN0603-DL	
DIM	(mm)
X	0.23
X1	0.61
Y	0.30



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